SCBS157F - JANUARY 1991 - REVISED MAY 1997

- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

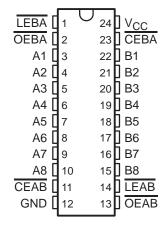
description

The 'ABT543A octal transceivers contain two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable (LEAB or LEBA) and output-enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow.

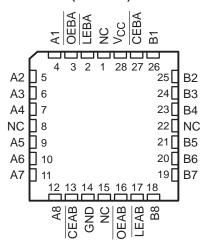
The A-to-B enable (\overline{CEAB}) input must be <u>low to</u> enter data from A or to output data from B. If \overline{CEAB} is low and \overline{LEAB} is low, the A-to-B latches are transparent; a subsequent low-to-high transition of \overline{LEAB} puts the A latches in the storage mode. With \overline{CEAB} and \overline{OEAB} both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar, but requires using the \overline{CEBA} , \overline{LEBA} , and \overline{OEBA} inputs.

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN54ABT543A . . . JT OR W PACKAGE SN74ABT543A . . . DB, DW, NT, OR PW PACKAGE (TOP VIEW)



SN54ABT543A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The SN54ABT543A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT543A is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated.



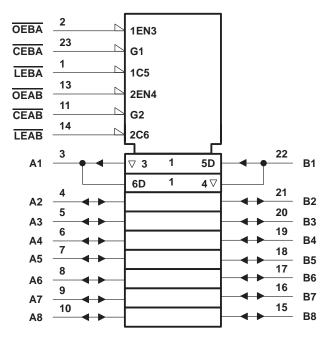
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FUNCTION TABLE†

	INPUTS									
CEAB	LEAB	OEAB	Α	В						
Н	Х	Х	Χ	Z						
Х	X	Н	X	Z						
L	Н	L	Χ	в ₀ ‡						
L	L	L	L	L						
L	L	L	Н	Н						

[†] A-to-B data flow is shown; B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.

logic symbol§

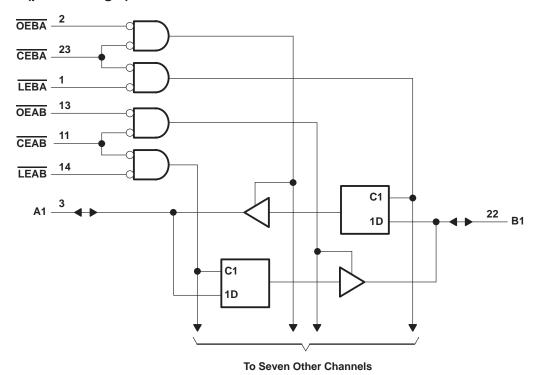


§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.



[‡]Output level before the indicated steady-state input conditions were established

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	\dots -0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V _O	0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT543A	96 mA
SN74ABT543A	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	
Package thermal impedance, θ _{JA} (see Note 2): DB package	104°C/W
DW package	
NT package	
PW package	
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.



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recommended operating conditions (see Note 3)

			SN54AB	T543A	SN74AB	T543A	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage			0.8		0.8	V
٧ _I	Input voltage		0	VCC	0	VCC	V
IOH	High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
TA	Operating free-air temperature		- 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DA	DAMETER	TEST CO.	NOITIONS	Т	A = 25°0	;	SN54AB	T543A	SN74AB	T543A	UNIT	
PAI	RAMETER	1551 CO	NDITIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNII	
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
VOH		$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		٧	
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				v	
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2			
VOL		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V	
V _{hys}					100						mV	
1.	Control inputs	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		±1		±1	μΑ	
lı .	A or B ports	VCC = 5.5 V,	1 = ACC 01 QMD			±100		±100		±100	μΑ	
lozH [‡]		$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			10§		10§		10§	μΑ	
l _{OZL} ‡		$V_{CC} = 5.5 V,$	V _O = 0.5 V			-10§		-10§		-10§	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ	
IO¶		V _{CC} = 5.5 V,	V _O = 2.5 V	-50*	-100	-180*	-50	-200	-50	-180	mA	
		V _{CC} = 5.5 V,	Outputs high		1	250*		350		250	μΑ	
Icc	A or B ports	$I_{O} = 0$,	Outputs low		24	30*		34		30	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250*		350		250	μΑ	
∆l _{CC} #	V _{CC} = 5.5 V, One i Other inputs at V _C (1.5		1.5		1.5	mA	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			4						pF	
C _{io}	A or B ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$			7						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



[†] All typical values are at V_{CC} = 5 V. ‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] This data sheet limit may vary among suppliers.

 $[\]P$ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $^{^{\#}}$ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

					SN54AE	3T543A		
				V _{CC} =	= 5 V, 25°C	MIN	MAX	UNIT
			MIN	MAX				
t _W	Pulse duration, LEAB or LEBA low			3.5		3.5		ns
		Data hafara LEAD or LEDA	a before LEAB or LEBA↑ High 2.5			2.5		
۱.	Setup time	Data before LEAD of LEDAT	Low	3		3		ns
t _{su}	Setup time	Data before CEAB or CEBA↑	High	2.5		2.5		115
		Data before CEAB or CEBA	Low	3		3		
.	Hold time	Data after LEAB or LEBA↑		1		1		ns
th	i ioia time	Data after CEAB or CEBA↑		1		1		115

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

					SN74AE	3T543A		
				V _{CC} =	= 5 V, 25°C	MIN	MAX	UNIT
				MIN	MAX			
t _W	Pulse duration, LEAB or LEBA low			3.5		3.5		ns
		Data before <u>LEAB</u> or <u>LEBA</u> ↑	High	3.5		3.5		
	Setup time	Data before LEAB of LEBA	Low	3		3		ns
t _{su}	Setup time	Data before CEAB or CEBA↑	High	3.5		3.5		115
		Data before CEAB of CEBA	Low	3		3		
+.	Hold time	Data after LEAB or LEBA↑	Data after LEAB or LEBA↑			0.5		ns
th	Hold time	Data after CEAB or CEBA↑		0.5		0.5	·	115

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

				SN5	4ABT54	3A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V A = 25°C	', ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	A or B	B or A	1.6†	4.4	4.4	1.6†	5.5	ns
t _{PHL}	AOIB	BULK	1.6	4.4	5.1	1.6	6.2	115
tPLH	LEBA or LEAB	A or B	1.6†	4.1	5.1	1.6†	6.6	ns
^t PHL	LEDA OI LEAD	AOID	1.6	4.6	5.4	1.6	6.4	115
^t PZH	OEBA or OEAB	A or B	1.4	3.9	4.1	1.4	5.1	ns
tPZL	OEBA OF OEAB	AUID	2	5	4.9	2	5.8	115
^t PHZ	OEBA or OEAB	A or B	2.5†	5.9	5.8	2.5†	6.9	ns
^t PLZ	OEDA OI OEAD	AOID	2.5†	5.5	6.1	2.5†	7.6	115
^t PZH	CEBA or CEAB	A or B	1.4	3.9	4.7	1.4	5.6	ns
tPZL	CEBA OF CEAB	AUID	2	5	5.7	2	6.2	115
^t PHZ	CEBA or CEAB	A or B	3.2†	5.9	6.5	3.2†	7.3	ne
t _{PLZ}	OLDA OI OLAD	AUID	2.5†	5.5	6.7	2.5†	7.8	ns

[†] This data sheet limit may vary among suppliers.

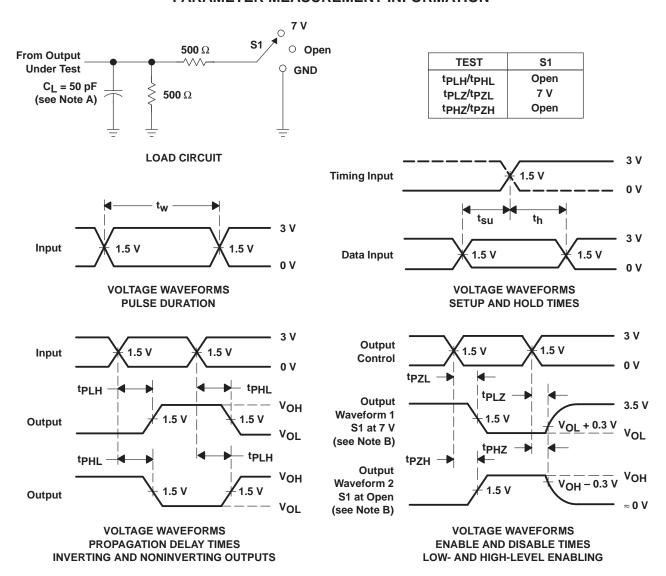
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

				SN7	4ABT54	3A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)		CC = 5 V 4 = 25°C		MIN	MAX	UNIT
			MIN	TYP	MAX			
^t PLH	A or B	B or A	1.8†	4.4	5.9	1.8†	6.9	ns
^t PHL	AUID	BUIA	1.9	4.4	5.9	1.9	6.9	115
^t PLH	LEBA or LEAB	A or B	1.5†	4.1	5.6	1.5†	6.6	ns
^t PHL	LEBA OF LEAB	AUID	2.1	4.6	6.1	2.1	7.1	115
^t PZH	OEBA or OEAB	or OEAB A or B	1.4	3.9	5.4	1.4	6.4	ns
t _{PZL}	OEBA 01 OEAB	AOIB	2.5	5	6.5	2.5	7.5	115
^t PHZ	OEBA or OEAB	A or B	2.5†	5.9	7.4	2.5†	8.4	ns
^t PLZ	OEBA OF OEAB	AUID	2.5†	5.5	7	2.5†	8	115
^t PZH	<u> </u>	A or B	1.4	3.9	5.4	1.4	6.4	
t _{PZL}	CEBA or CEAB	AOIB	2.5	5	6.5	2.5	7.5	ns
^t PHZ	CEBA or CEAB	A or D	2.9†	5.9	7.4	2.9†	8.4	
tPLZ	CEDA UI CEAD	A or B	2.4†	5.5	7	2.4†	8	ns

[†] This data sheet limit may vary among suppliers.



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9231402Q3A	ACTIVE	LCCC	FK	28	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9231402Q3A SNJ54 ABT543AFK	Samples
SN74ABT543ADBR	ACTIVE	SSOP	DB	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A	Samples
SN74ABT543ADBRG4	ACTIVE	SSOP	DB	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A	Samples
SN74ABT543ADW	ACTIVE	SOIC	DW	24	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A	Samples
SN74ABT543ADWR	ACTIVE	SOIC	DW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A	Samples
SN74ABT543APW	ACTIVE	TSSOP	PW	24	60	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A	Samples
SN74ABT543APWR	ACTIVE	TSSOP	PW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A	Samples
SNJ54ABT543AFK	ACTIVE	LCCC	FK	28	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9231402Q3A SNJ54 ABT543AFK	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

PACKAGE OPTION ADDENDUM

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(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ABT543A, SN74ABT543A:

Catalog: SN74ABT543A

Military: SN54ABT543A

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT543ADBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74ABT543ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ABT543APWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

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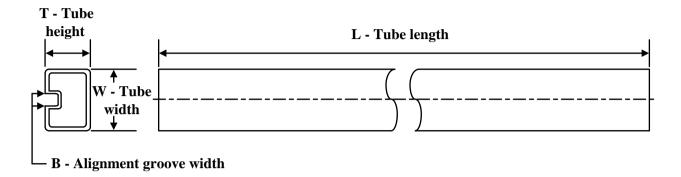
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT543ADBR	SSOP	DB	24	2000	356.0	356.0	35.0
SN74ABT543ADWR	SOIC	DW	24	2000	350.0	350.0	43.0
SN74ABT543APWR	TSSOP	PW	24	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

	Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
ĺ	SN74ABT543ADW	DW	SOIC	24	25	506.98	12.7	4826	6.6
ĺ	SN74ABT543APW	PW	TSSOP	24	60	530	10.2	3600	3.5

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



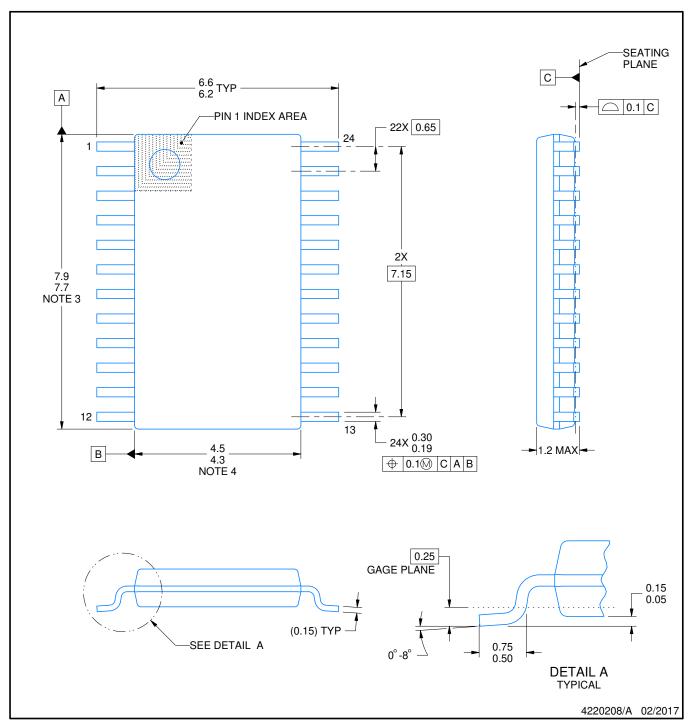
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004





SMALL OUTLINE PACKAGE



NOTES:

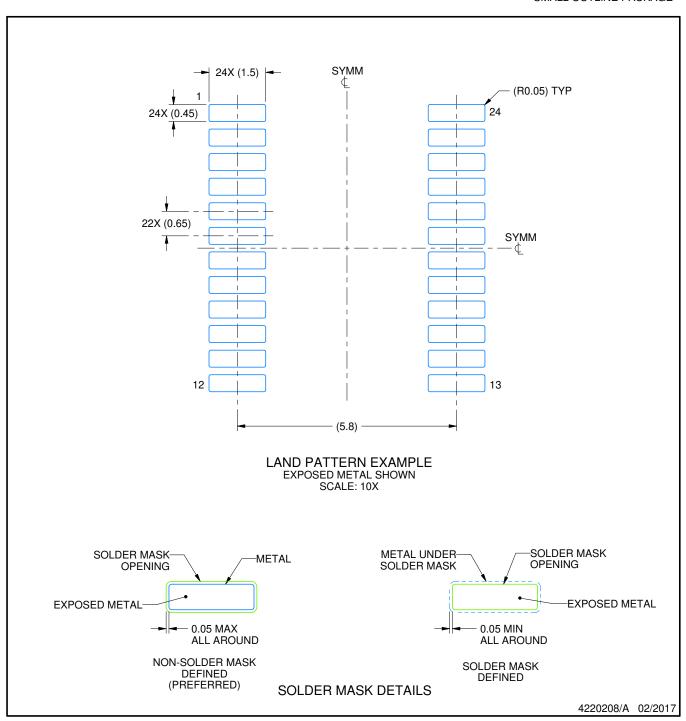
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



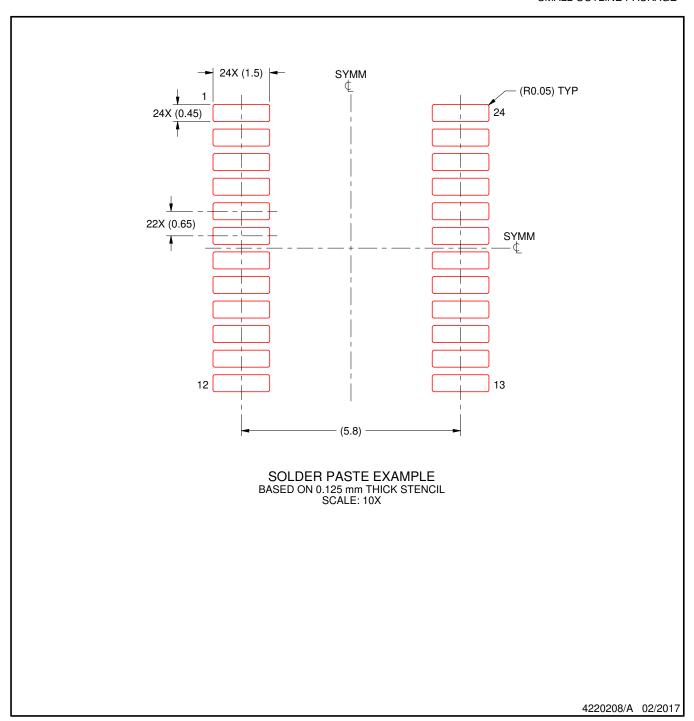
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



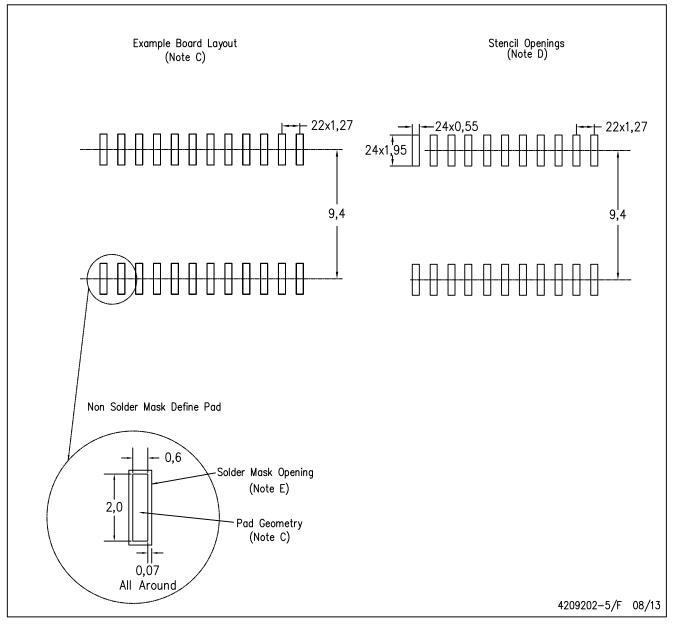
NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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